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Flexible
Solvent Free
High Green Strength
Electrically Conductive
Epoxy Paste Adhesive

IDEAL FOR:

- "No" Bleeding
- Large Area Die Attach
- Screen-Printable
- Component Attach
- Substrate Attach

DESCRIPTION:

ME8550-DA is a die attach epoxy paste adhesive designed for needle dispensing and screen-printing processing. This silver filled conductive die-attach adhesive can be rapidly cured at low temperatures. This single component, silver filled paste is electrically and thermally conductive. It is thixotropic with minimal sag.

ME8550-DA has been designed to eliminate bleeding on both silver plated copper and alloy 42 leadframes.

AVAILABILITY:

ME8550-DA is available in syringes or in jars.

APPLICATION PROCEDURES:

- (1) Thaw for 30 min. before opening jar or using syringes.
- (2) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.
- (3) Cure according to the recommended schedules.

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details
 The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

While AI Technology owns all proprietary rights of material formulations of its products, specific usage in the manufacturing of certain products may involve patent rights of other companies.

DIE ATTACH ADHESIVE
ME8550-DA

TYPICAL PROPERTIES*

| | |
|---|--|
| Electrical Resistivity (150 °C/ 30 minute) | <1x10⁻³ ohm-cm |
| Dielectric Strength (Volts/mil) | >Not Applicable |
| Glass Transition Temp.(°C) | -55 ±10% |
| Current Carrying Capabilities | 50 Amp/mm² |
| Lap-Shear Strength | >~500 psi >~3.4 N/mm² |
| Device Push-off Strength | >1000 psi >6.9 N/mm² |
| Hardness (Type) | 90 (A) ±10% |
| Cured Density (gm/cc) | 3.8 ±10% |
| Thermal Conductivity | >55 Btu-in/hr-ft²-°F ±10% >7.9 W/m-°C ±10% |
| Linear Thermal Expansion Coeff. (ppm/°C) | 100 ±15% |
| Maximum Continuous Operation Temp. (°C) | <150 |
| Avg. Viscosity(5.0 rpm, 25°C) (Brookfield DV-1,spindle CP51) | 40,000 cp ±20% |

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CURE SCHEDULES:

| <u>Temperature</u> | <u>Time</u> | <u>Pressure</u> |
|--------------------|-------------|-----------------|
| 85°C | 4 hr | |
| 100°C | 2 hr | |
| 125°C | 1 hr | |
| 150°C | 30 min | |

Pot life: 25°C for 2 days.

SHELF LIFE:

| <u>Storage temperature</u> | <u>Shelf Life</u> |
|----------------------------|-------------------|
| -40°C | 1 yr |
| 25°C | 2 days |